

## EGP10A - EGP10K

### **Features**

- Superfast recovery time for high efficiency.
- Low forward voltage, high current capability.
- · Low leakage current.
- High surge current capability.



DO-41
COLOR BAND DENOTES CATHODE

## 1.0 Ampere Glass Passivated High Efficiency Rectifiers

### **Absolute Maximum Ratings\*** T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Symbol Parameter		Units	
I <sub>F(AV)</sub>	Average Rectified Current .375 " lead length @ T <sub>L</sub> = 55°C	1.0	А	
I <sub>FSM</sub>	Non-repetitive Peak Forward Surge Current 8.3 ms single half-sine-wave Superimposed on rated load (JEDEC method)	30	А	
P <sub>D</sub>	Total Device Dissipation Derate above 25°C	2.5 17	W mW/°C	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	50	°C/W	
T <sub>stg</sub>	Storage Temperature Range	-65 to +150	°C	
TJ	Operating Junction Temperature	-65 to +150	°C	

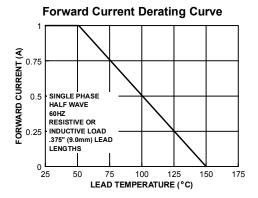
<sup>\*</sup>These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

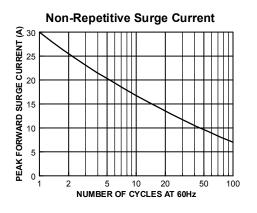
### Electrical Characteristics T. = 25°C

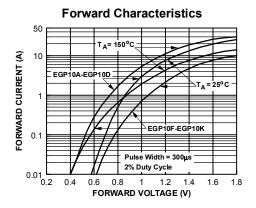
T <sub>A</sub>	= 25°	C unless	otherwise	noted
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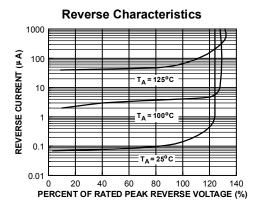
Symbol Parameter		Device						Units		
		10A	10B	10C	10D	10F	10G	10J	10K	
$V_{RRM}$	Maximum Repetitive Reverse Voltage	50	100	150	200	300	400	600	800	V
V <sub>RMS</sub>	Maximum RMS Voltage		70	105	140	210	280	420	560	V
V <sub>R</sub>	DC Reverse Voltage (Rated V <sub>R</sub> )	50 100 150 200 300 400 600 800		V						
I <sub>RM</sub>	Maximum Instantaneous Reverse Current @ rated $V_R$ $T_A = 25^{\circ}C$ 5.0 $T_A = 125^{\circ}C$ 100					μ <b>Α</b> μ <b>Α</b>				
trr	Maximum Reverse Recovery Time I <sub>F</sub> = 0.5 A, I <sub>R</sub> = 1.0 A, I <sub>rr</sub> = 0.25 A	50 75		ns						
V <sub>FM</sub>	Maximum Instantaneous Forward Voltage @ 1.0 A	0.95 1.25 1.7		V						
С	Typical Junction Capacitance V <sub>R</sub> = 4.0 V, f = 1.0 MHz	22 15		5		pF				

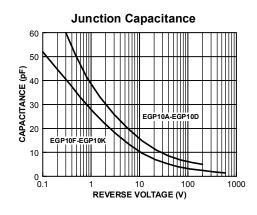
### **Typical Characteristics**

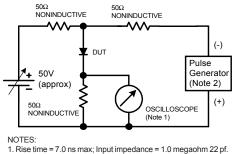




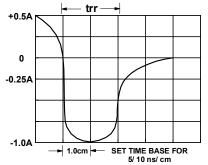








2. Rise time = 10 ns max; Source impedance = 50 ohms.

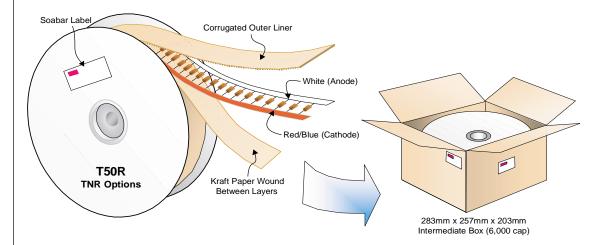


Reverse Recovery Time Characterstic and Test Circuit Diagram

### DO-41 (Glass) Tape and Ammo Data



## DO-41 (Glass) Packaging Configuration: Figure 1.0



## DO-41 (Glass) Packaging Information

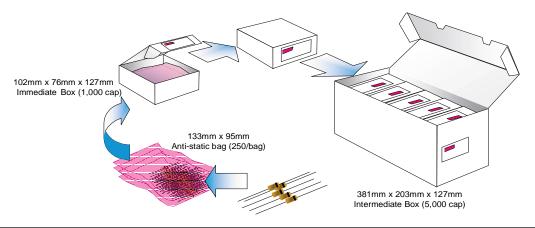
Table: Figure 2.0

DO-41 (Glass) Packaging Information						
Packaging Option	T50R	T50A	Standard (no flow code)			
Packaging type	TNR Ammo		Bag			
Qty per Reel/Tube/Bag	eel/Tube/Bag 3,000 3,000		250			
Reel Size (inch diameter)	10.5	-	-			
Inside Tape Spacing (mm)	52	52	-			
Int Box Dimension (mm)	283x257x203	406x267x184	381x203x127			
Max qty per Box	6,000	30,000	5,000			
Weight per unit (gm)	0.320	0.320	0.320			
Weight per Reel (kg)	1.356	1.077	-			
Note/Comments			Bulk			

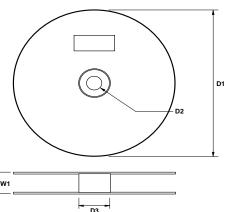
### Soabar Label sample

SEMICO	NDUCTOR 14	P.O. No.	
TYPE	1N4744A	MARK	BLK-BRN
REV	A2	PART No.	
PKG		EC No.	
QTY	3,000	M.O. No.	OX5046F035
Q.C.		DATE	D9903
MFD. UN	DER US PAT 3.025.589	& OTHER US PATS 8	APPLICATIONS

# **DO-41 (Glass) Bulk Packing Configuration:** Figure 3.0



### DO-41 (Glass) Tape and Ammo Data, continued DO-41 (Glass) Ammo Packing Configuration: Figure 4.0 254mm x 79mm x 79mm Immediate Container (3,000 cap) T50A Option 406mm x 267mm x 184mm rmediate Container (50,000 cap) for T50A option DO-41 (Glass) Taping **Dimension:** Figure 5.0 TAPING DIMENSIONS NOTES INCH MILS Overall width 2.047±0.027 52 ±0.69 2047±27 Inside Tape Spacing 0.200 ±0.0157 5.08 ±0.40 200 ±15.7 Component Pitch 0.047(max) 1.2(max) 47(max) Component Misalignmen 0.022(max) 0.55(max) 22(max) Tape Mismatch 0.027(max) ±0.69 ±27 Units in line w/ one another 0.126(min) 3.2(min) 126(min) Lead amount between tapes Lead amount beyond tapes L1-L2 ±0.027 ±0.69 ±27 Delta between two leads DO-41 (Glass) Reel Dimension: Figure 6.0



REEL DIMENSIONS ITEM DESCRIPTION	SYMBOL	MINIMUM	MAXIMUM
Reel Diameter	D1	10.375	10.625
Arbor Hole Diameter (Standard)	D2	1.245	1.255
Core Diameter	D3	3.190	3.310
Flange to Flange Outer Width	W1		3.400

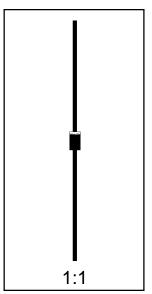
Note: All Dimensions are in inches

### **DO-41 (Glass) Package Dimensions**



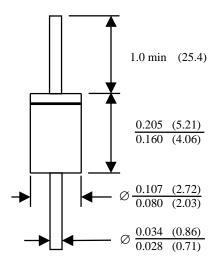
# DO-41 (FS PKG Code D4)





Scale 1:1 on letter size paper
Dimensions shown below are in:
inches [millimeters]

Part Weight per unit (gram): 0.32



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DOME™ ISOPLANAR™ Quiet Series™

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